

# **RADIAL CONTACT PAD FOOTPRINT AND WIRING FOR ELECTRICAL COMPONENTS**

## **Abstract of the Disclosure**

A structure and associated method comprising contact pads on a surface of a substrate for  
5 coupling signal, power, and ground connections for an electrical device to a plurality of  
conductive wires on the substrate. The contact pads are formed in single lines along radial edges  
of sectors on the substrate. Each of the sectors comprise a predetermined angle between the  
radial edges of each of the sectors. The plurality of sectors collectively form a circular area. The  
contact pads comprise signal, power, and ground connections located at predetermined positions  
10 on the single lines along the radial edges of each of the sectors on the substrate.